

Process dependent interface strengthening, de-icing and EMI shielding performance in PEEK/CF laminates

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Recyclability Studies:

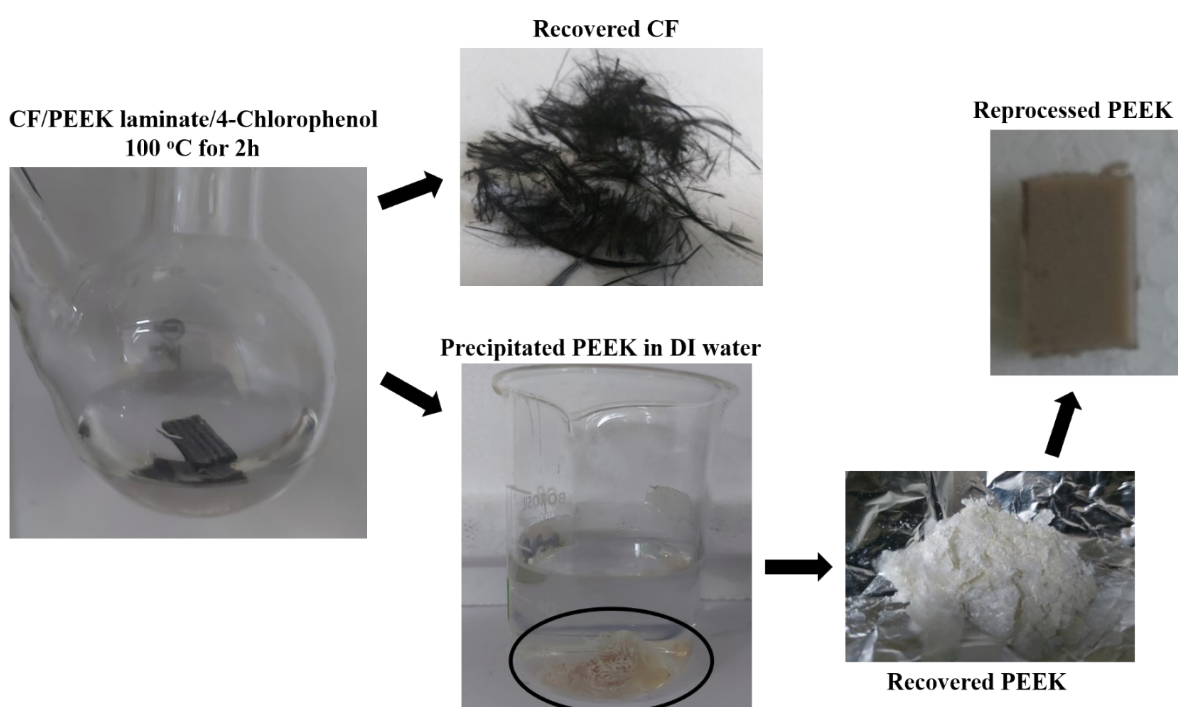


Figure S1: Recyclability process of CF/PEEK

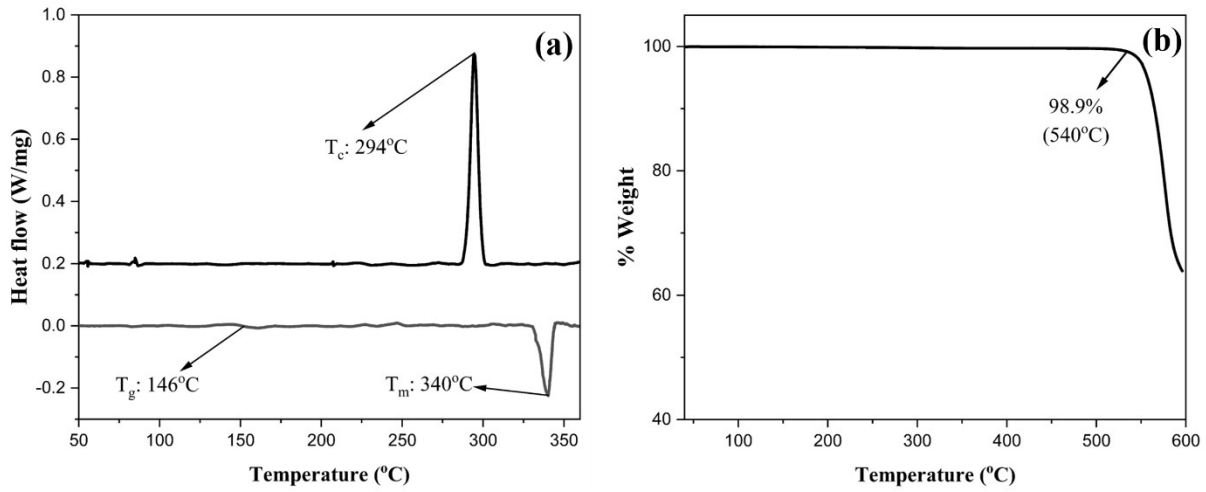


Figure S2: (a) DSC thermogram of PEEK, (b) TGA plot of PEEK

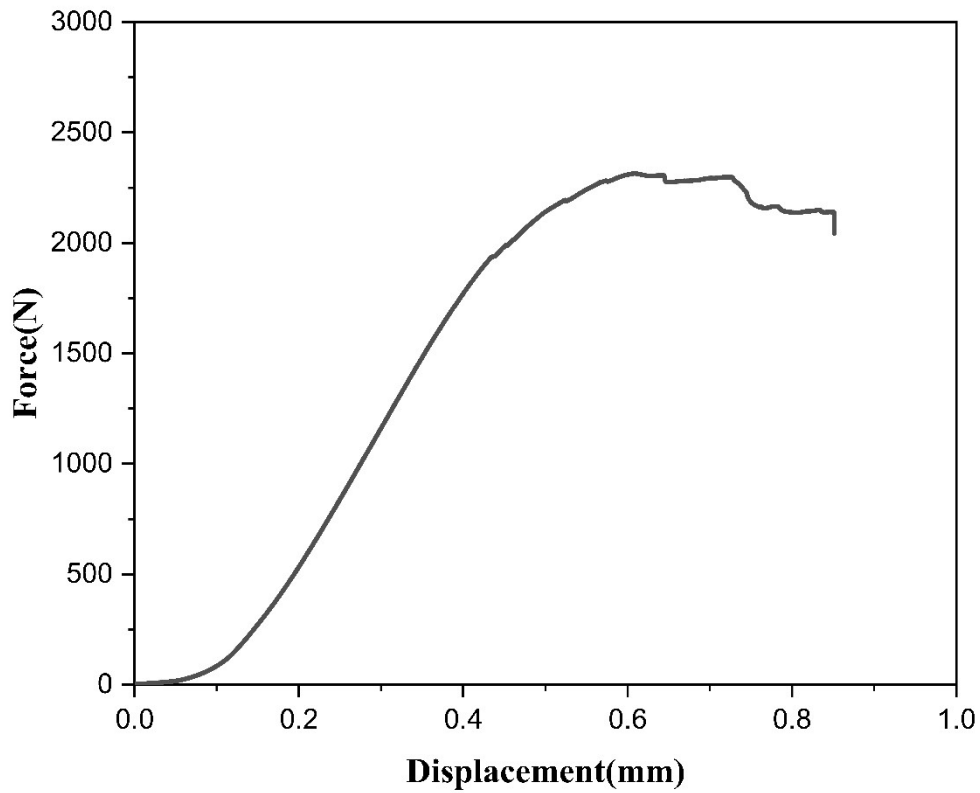


Figure S3: Representative Load vs displacement plot of sample L4.

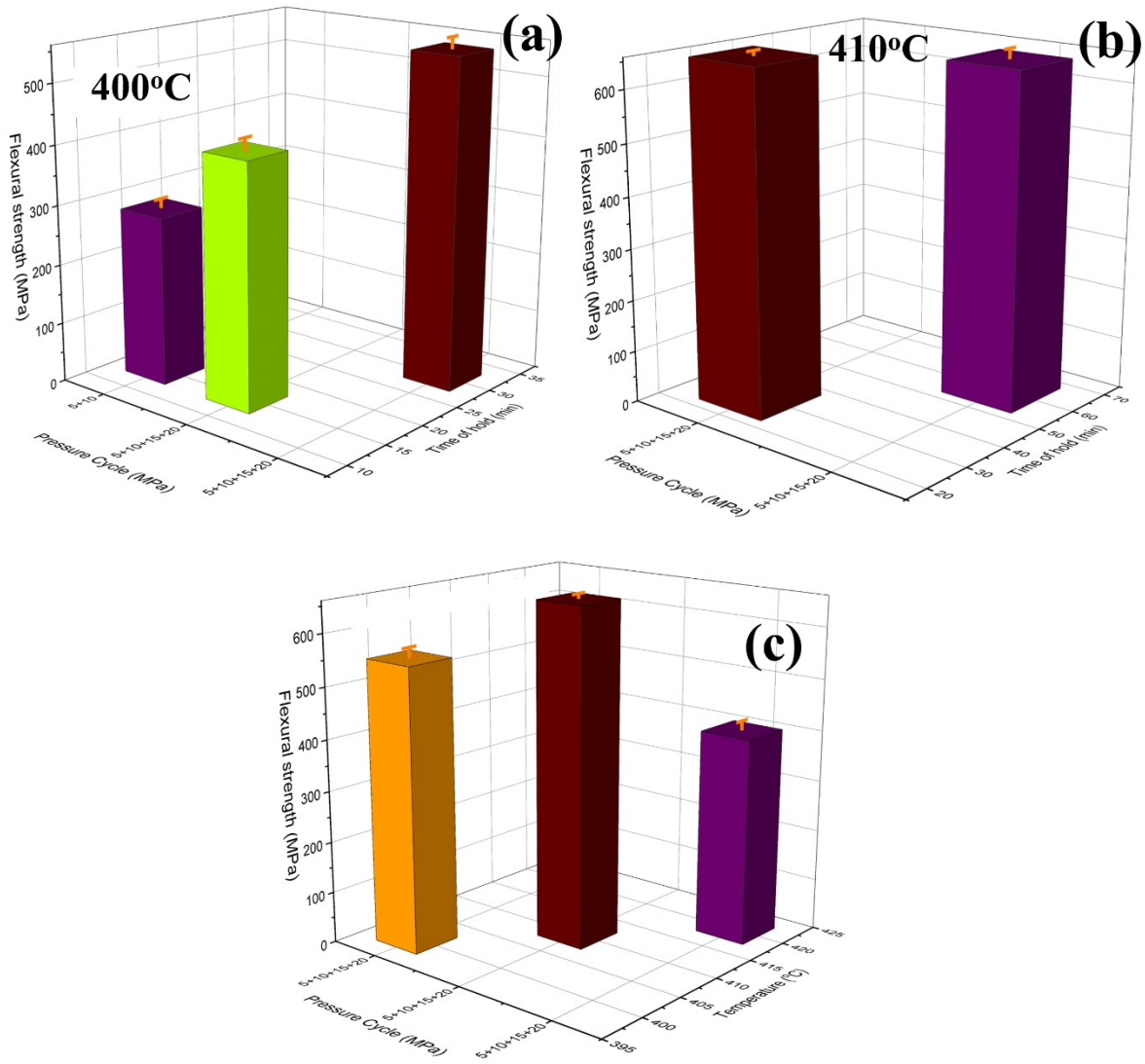


Figure S4: FS values of CF/PEEK laminates (a) Variation of pressure cycle and holding time at 400°C; (b) variation of holding time at 400°C; (c) variation of processing temperature for 5+10+15+20MPa pressure cycle and 30min holding time.